

# **Product Change Notification - KSRA-22HOHO409**

Date:

21 May 2020

**Product Category:** 

**Ethernet PHYs** 

**Affected CPNs:** 



### **Notification subject:**

CCB 3837 Cancelation Notice: Qualification of LMC-705VF mold compound material for Microsemi VSC8248YJH-02 catalog part number (CPN) available in 225L FCCSP package at SFA1 assembly site.

#### **Notification text:**

#### **PCN Status:**

Cancelation notification

## **Microchip Parts Affected:**

This change would have affected VSC8248YJH-02 catalog part number (CPN) available in 225L FCCSP package.

## **Description of Change:**

This qualification was originally performed to implement LMC-705VF mold compound material for Microsemi VSC8248YJH-02 catalog part number (CPN) available in 225L FCCSP package at SFA1 assembly site.

### Impacts to Data Sheet:

Not applicable

## **Change Impact:**

Not applicable

### **Reason for Change:**

Microchip has decided not to implement LMC-705VF mold compound for Microsemi VSC8248YJH-02 catalog part number (CPN) available in 225L FCCSP package at SFA1 assembly site.

## **Change Implementation Status:**

Not applicable

## **Revision History:**

August 14, 2019: Issued initial notification.

**February 28, 2020:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on March 27, 2020. Revised subject to more accurately depict changes.

May 22, 2020: Issued cancelation notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachment(s):



Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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| Affected Catalog Part Numbers (CPN)  |
| VSC8248YJH-02  |
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| Date: Thursday, May 21, 2020   |